

1.1. S34ML-1 Product Families

41 nm SLC NAND

41 nm SLC NAND were introduced in Jun 2012 and utilize tunnel Oxide, Polysilicon floating gate and interconnections are three metal layers with contact plugs and barrier metals. The 1st Metal layer for 41 nm SLC NAND is using Copper.

Data Summary and Failure Rate Estimation using Exponential Model HTOL Stress Temperature - 125°C

Failure Mechanisms	Read Point / Test Result		Modeling Parameters @ 55°C					Average Failure Rate	
	Early Life (hrs)	Inherent Life (hrs)	Ea eV	TAF	VAF	OAF	MTTF (yrs)	Early Life (PPM)	Inherent Life (FITS)
	96	1000							
Sample Size 125C, Zero fails, Process ave. Ea	500 0	150 0	0.7	74	1	74	9259	0	12

Data Retention Bake - 150°C

Reliability Stress	Sample Size	Reject	PPM	FITS
1000	77	0	0	<1

Endurance - 90°C

Reliability Stress	Sample Size	Reject	PPM	FITS
10000	60	0	0	2
100000(Decade)	64	0	0	

1.2. S34ML-2 Product

Families

32 nm SLC NAND

32 nm SLC NAND were introduced in October 2012 and utilize tunnel Oxide, Polysilicon floating gate and interconnections are three metal layers with contact plugs and barrier metals. The 1st Metal layer for 32 nm SLC NAND is using Copper

Data Summary and Failure Rate Estimation using Exponential Model HTOL Stress Temperature - 125°C

Failure Mechanisms	Read Point / Test Result		Modeling Parameters @ 55°C					Average Failure Rate	
	Early Life (hrs)	Inherent Life (hrs)	Ea eV	TAF	VAF	OAF	MTTF (yrs)	Early Life (PPM)	Inherent Life (FITS)
	96	1000							
Sample Size	500	150							
125C, Zero fails, Process ave. Ea	0	0	0.7	74	1	74	12198	0	9

Data Retention Bake - 150°C

Reliability Stress	Sample Size	Reject	PPM	FITS
1000	77	0	0	<1

Endurance - 90°C

Reliability Stress	Sample Size	Reject	PPM	FITS
10000	60	0	0	2
100000(Decade)	64	0	0	

1.3. S34ML-3 Product

Families

16 nm SLC NAND

16 nm SLC NAND were introduced in November 2019 and utilize tunnel Oxide, Polysilicon floating gate and interconnections are three metal layers with contact plugs and barrier metals. The 1st Metal layer for 16 nm SLC NAND is using Copper

Data Summary and Failure Rate Estimation using Exponential Model HTOL Stress Temperature - 125°C

Failure Mechanisms	Read Point / Test Result		Modeling Parameters @ 55°C					Average Failure Rate	
	Early Life (hrs)	Inherent Life (hrs)	Ea eV	TAF	VAF	OAF	MTTF (yrs)	Early Life (PPM)	Inherent Life (FITS)
	96	1000							
Sample Size 125C, Zero fails, Process ave. Ea	500 0	150 0	0.66	61	1	62	5708	79	20

Data Retention Bake - 150°C

Reliability Stress	Sample Size	Reject	PPM	FITS
1000	77	0	0	<1

Endurance - 90°C

Reliability Stress	Sample Size	Reject	PPM	FITS
10000	60	0	0	2
100000(Decade)	64	0	0	

2. Data Summaries by Package Family

BGA (Ball Grid Array)

Reliability Stress	Sample Size	Reject	Failure Rate PPM
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HAST	96hrs	1766	0	0
	264hrs	3893	0	0
HIGH TEMP STORAGE	1000hrs	5632	0	0
TEMP CYCLE	500cycle	3981	0	0
	1000cycle	2699	0	0
UNBIASED HAST TEST	96hrs	4237	0	0
	264hrs	1528	0	0

TSOP (Thin Small Outline Package)

Reliability Stress		Sample Size	Reject	Failure Rate PPM
HAST	96hrs	3783	0	0
	264hrs	75	0	0
HIGH TEMP STORAGE	1000hrs	5687	0	0
PRESSURE COOKER TEST	96hrs	120	0	0
	168hrs	2241	0	0
TEMP CYCLE	500cycle	5449	0	0
UNBIASED HAST TEST	96hrs	2147	0	0

BGA 153 (Ball Grid Array)

Reliability Stress		Sample Size	Reject	Failure Rate PPM
PC	192hrs	100	0	0
HAST	164hrs	25	0	0
HIGH TEMP STORAGE	1000hrs	25	0	0
TEMP CYCLE	500cycle	25	0	0
UNBIASED HAST TEST	96hrs	25	0	0

SkyHigh Memory